

LOW V_{CE(SAT)} NPN SURFACE MOUNT TRANSISTOR

Features

- **Epitaxial Planar Die Construction**
- Complementary PNP Type Available (DPLS350E)
- Ideally Suited for Automated Assembly Processes
- Ideal for Medium Power Switching or Amplification Applications
- Lead Free By Design/RoHS Compliant (Note 1)
- "Green" Device (Note 2)

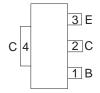
Mechanical Data

- Case: SOT-223
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020D
- Terminals: Finish Matte Tin annealed over Copper leadframe (Lead Free Plating). Solderable per MIL-STD-202, Method 208
- Marking Information: See Page 4
- Ordering Information: See Page 4
- Weight: 0.115 grams (approximate)



Top View





Device Schematic

COLLECTOR

Pin Out Configuration

Maximum Ratings @T_A = 25°C unless otherwise specified

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V _{CBO}	60	V
Collector-Emitter Voltage	V _{CEO}	50	V
Emitter-Base Voltage	V _{EBO}	6	V
Peak Pulse Collector Current	I _{CM}	5	A
Continuous Collector Current	Ic	3	Α
Peak Pulse Base Current	I _{BM}	1	А

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 3) @ T _A = 25°C	P_{D}	1	W
Thermal Resistance, Junction to Ambient Air (Note 3) @ T _A = 25°C	$R_{ heta JA}$	125	°C/W
Power Dissipation (Note 4) @ T _A = 25°C	P_{D}	2	W
Thermal Resistance, Junction to Ambient Air (Note 4) @ T _A = 25°C	$R_{ heta JA}$	62.5	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +150	°C

Notes:

- 1. No purposefully added lead.
- 2. Diodes Inc.'s "Green" policy can be found on our website at http://www.diodes.com/products/lead_free/index.php.
- 3. Device mounted on FR-4 PCB; pad layout as shown on page 4 or in Diodes Inc. suggested pad layout document AP02001, which can be found on our website at http://www.diodes.com/datasheets/ap02001.pdf.
- 4. Device mounted on FR-4 PCB with 1inch² copper pad layout.



Electrical Characteristics @T_A = 25°C unless otherwise specified

Characteristic	Symbol	Min	Тур	Max	Unit	Test Conditions
OFF CHARACTERISTICS					_	
Collector-Base Cutoff Current	lone		_	100	nA	$V_{CB} = 50V, I_{E} = 0$
Collector-base Cutoff Current	ICBO	_	_	50	μΑ	$V_{CB} = 50V, I_E = 0, T_A = 150$ °C
Emitter-Base Cutoff Current	I _{EBO}	_		100	nA	$V_{EB} = 5V, I_C = 0$
Collector-Base Breakdown Voltage	V _{(BR)CBO}	50	_	_	V	$I_C = 100 \mu A$
Collector-Emitter Breakdown Voltage (Note 5)	V _{(BR)CEO}	50		_	V	$I_C = 10mA$
Emitter-Base Breakdown Voltage	V _{(BR)EBO}	5	_	_	V	$I_E = 100 \mu A$
ON CHARACTERISTICS (Note 5)						_
		200	_	_		$V_{CE} = 2V, I_{C} = 0.5A$
DC Current Gain	h _{FE}	200	_	_	_	$V_{CE} = 2V$, $I_C = 1A$
		100		_		$V_{CE} = 2V$, $I_C = 2A$
Collector-Emitter Saturation Voltage	·	_	_	90	mV	$I_C = 0.5A, I_B = 50mA$
	V _{CE(SAT)}	_		170		$I_C = 1A$, $I_B = 50mA$
		_		290		$I_C = 2A$, $I_B = 200mA$
Equivalent On-Resistance	R _{CE(SAT)}	_	62	145	$m\Omega$	$I_E = 2A$, $I_B = 200mA$
Base-Emitter Saturation Voltage	V _{BE(SAT)}	_		1.2	V	$I_C = 2A$, $I_B = 200mA$
Base-Emitter Turn-on Voltage	V _{BE(ON)}	_	_	1.1	V	$V_{CE} = 2V$, $I_C = 1A$
SMALL SIGNAL CHARACTERISTICS						
Transition Frequency	f _T	100	_	_	MHz	$V_{CE} = 5V, I_{C} = 100mA,$ f = 100MHz
Output Capacitance	C _{obo}		_	30	pF	V _{CB} = 10V, f = 1MHz

Notes: 5. Measured under pulsed conditions. Pulse width = 300μ s. Duty cycle $\leq 2\%$.

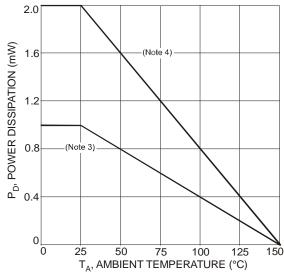


Fig. 1 Max Power Dissipation vs. Ambient Temperature

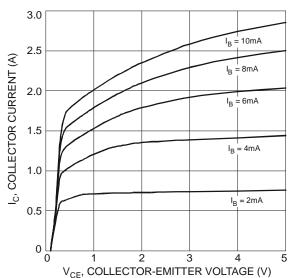
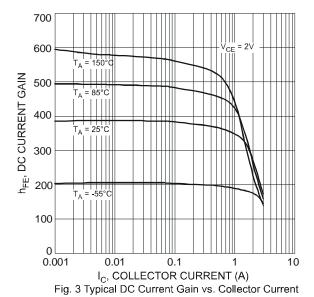
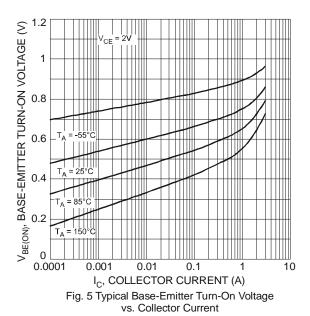
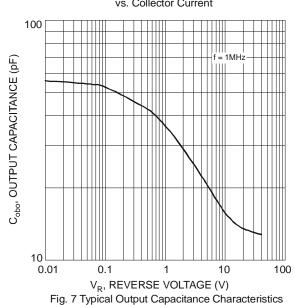


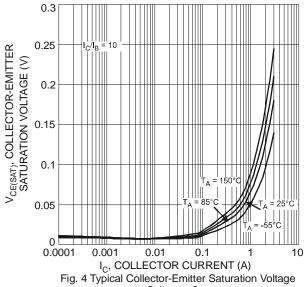
Fig. 2 Typical Collector Current vs. Collector-Emitter Voltage











vs. Collector Current

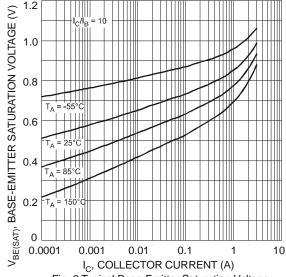


Fig. 6 Typical Base-Emitter Saturation Voltage vs. Collector Current

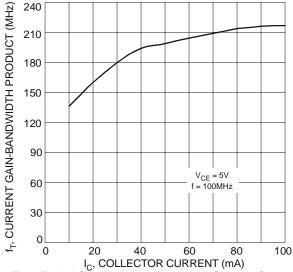


Fig. 8 Typical Gain-Bandwidth Product vs. Collector Current

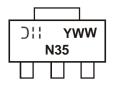


Ordering Information (Note 6)

Part Number	Case	Packaging
DNLS350E-13	SOT-223	2500/Tape & Reel

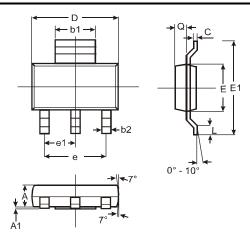
Notes: 6. For packaging details, go to our website at http://www.diodes.com/datasheets/ap02007.pdf.

Marking Information



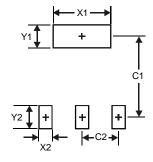
N35 = Product Type Marking Code YWW = Date Code Marking Y = Last digit of year (ex: 7 = 2007) WW = Week code 01 - 52

Package Outline Dimensions



SOT-223			
Dim	Min	Max	Тур
Α	1.55	1.65	1.60
A1	0.010	0.15	0.05
b1	2.90	3.10	3.00
b2	0.60	0.80	0.70
С	0.20	0.30	0.25
D	6.45	6.55	6.50
Е	3.45	3.55	3.50
E1	6.90	7.10	7.00
е		_	4.60
e1		_	2.30
L	0.85	1.05	0.95
q	0.84	0.94	0.89
All Dimensions in mm			

Suggested Pad Layout



Dimensions	Value (in mm)
X1	3.3
X2	1.2
Y1	1.6
Y2	1.6
C1	6.4
C2	2.3



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